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DOCKET NO. B3-4282

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Weidan Li, Wen-Chin Yeh, and Rajat Rakkhit

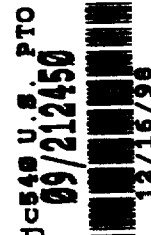
Assignee: LSI Logic Corporation

Title: TUNGSTEN LOCAL INTERCONNECT FOR SILICON INTEGRATED CIRCUIT STRUCTURES, AND METHOD OF MAKING SAME

Serial No.: Unknown

Filed: Herewith Group Art Unit: Unknown

Attorney Docket No. B3-4282 Examiner: Unknown



December 16, 1998

RECORDATION FORM COVER SHEET PATENTS ONLY

To the Honorable Commissioner  
of Patents and Trademarks  
Washington, DC 20231

Sir:

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Weidan Li

Date of Execution: December 11, 1998

Wen-Chin Yeh

Date of Execution: December 14, 1998

Rajat Rakkhit

Date of Execution: December 14, 1998

12/23/1998 SRUENS 00000103 09212450

FC:581

40.00 BP

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PATENT  
REEL: 9654 FRAME: 0343

2. Name and address of receiving party(ies):

LSI Logic Corporation  
1551 McCarthy Boulevard  
Milpitas, California 95035  
U.S.A.

3. Nature of conveyance: Assignment

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: December 11, 1998, December 14, 1998, and December 14, 1998

A. Patent Application Serial Number: \_\_\_\_\_

B. Patent Number: \_\_\_\_\_

5. Name and address of party to whom correspondence concerning document should be mailed:

John P. Taylor  
Post Office Box 1598  
Temecula, California 92593-1598  
U.S.A.

6. Total number of applications and patents involved: 1.

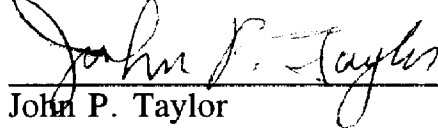
7. Total fee (37 CFR 3.41): \$40.00.

8. Attached is a check in the amount of \$ \_\_\_\_\_.

Charge Deposit Account No. \_\_\_\_\_ in the amount of \$ 40.00.

(A duplicate copy of this document is enclosed.)

9. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

  
\_\_\_\_\_  
John P. Taylor

Reg. No. 22,369

10. Total number of pages including cover sheet, attachments and document: 3.

**ASSIGNMENT**

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/WE, the undersigned, Weidan Li, Wen-Chin Yeh, and Rajat Rakkhit, do hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

( X ) which has been executed by the undersigned concurrently herewith,  
( ) which was filed on \_\_\_\_\_ 19\_\_\_\_ and assigned Serial No. \_\_\_\_\_.

and is entitled: "TUNGSTEN LOCAL INTERCONNECT FOR SILICON INTEGRATED CIRCUIT STRUCTURES, AND METHOD OF MAKING SAME" and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name: Weidan Li Date: Dec. 11, 1998

Witness: Leah Rosenthal  
Witness: \_\_\_\_\_  
Printed

Name: Wen-Chin Yeh Date: Dec. 14, 1998

Witness: Leah Rosenthal  
Witness: \_\_\_\_\_  
Printed

Name: Rajat Rakkhit Date: Dec. 14, 1998

Witness: Leah Rosenthal  
Witness: \_\_\_\_\_  
Printed

Name: \_\_\_\_\_ Date: \_\_\_\_\_, 1998

Witness: \_\_\_\_\_  
Witness: \_\_\_\_\_  
Printed